TMUX6119 ±16.5V, Low Capacitance, Low-Leakage-Current, Precision, SPDT Switch

1 Features

- Wide Supply Range: ±5V to ±16.5V (Dual) or 10V to 16.5V (Single)
- Latch-Up Performance Meets 100mA per JESD78 Class II Level A on all Pins
- Low On-Capacitance: 6.4pF
- Low Input Leakage: 5pA
- Low Charge Injection: 0.19pC
- Rail-to-Rail Operation
- Low On-Resistance: 120Ω
- Transition Time: 68ns
- Break-Before-Make Switching Action
- EN Pin and SEL Pin Connectable to V_{DD} with Integrated Pull-down
- Logic Levels: 2V to V_{DD}
- Low Supply Current: 17µA
- Human Body Model (HBM) ESD Protection: ±2kV on All Pins
- Industry-Standard SOT-23 Package

2 Applications

- Factory Automation and Industrial Process Controls
- Programmable Logic Controllers (PLC)
- Analog Input Modules
- ATE Test Equipment
- Digital Multimeters
- Battery Monitoring Systems

3 Description

The TMUX6119 is a modern complementary metal-oxide semiconductor (CMOS) single-pole, double throw (SPDT) switch. The device works well with dual supplies (±5V to ±16.5V), a single supply (10V to 16.5V), or asymmetric supplies. Both digital input pins (EN and SEL) have transistor-transistor logic (TTL) compatible thresholds, ensuring both TTL/ CMOS logic compatibility.

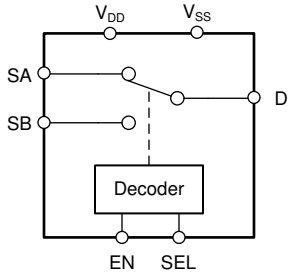
The TMUX6119 can be enabled or disabled by controlling the EN pin. When disabled, both channel switches are off. When enabled, the SEL pin can be used to turn on channel A (SA to D) or channel B (SB to D). Each channel conducts equally well in both directions and has an input signal range that extends to the supplies. The switches of TMUX6119 exhibit break-before-make (BBM) switching action.

The TMUX6119 is part of Texas Instruments Precision Switches and Multiplexers family. The TMUX6119 has very low leakage currents and charge injection, allowing the device to be used in high precision measurement applications. The device also provides excellent isolation capability by blocking signal levels up to the supplies when the switches are in the OFF position. A low supply current of 17µA enables usage in portable applications.

Package Information

PART NUMBER	PACKAGE (1)	BODY SIZE (NOM)
TMUX6119	SOT-23 (8)	2.90mm × 1.60mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



TMUX6119

Simplified Schematic

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

Table of Contents

1 Features....1
2 Applications....1
3 Description....1
4 Pin Configuration and Functions....3
Pin Functions....3
5 Specifications....4
5.1 Absolute Maximum Ratings....4
5.2 ESD Ratings....4
5.3 Thermal Information....4
5.4 Recommended Operating Conditions....5
5.5 Electrical Characteristics (Dual Supplies: ±15V)....5
5.6 Switching Characteristics (Dual Supplies: ±15V)....6
5.7 Electrical Characteristics (Single Supply: 12V)....7
5.8 Switching Characteristics (Single Supply: 12V)....8
5.9 Typical Characteristics....9
6 Parameter Measurement Information....12
6.1 Truth Tables....12
7 Detailed Description....13
7.1 Overview....13
7.2 Functional Block Diagram....20
7.3 Feature Description....20
7.4 Device Functional Modes....22
8 Application and Implementation....22
8.1 Application Information....22
8.2 Typical Application....22
9 Power Supply Recommendations....24
10 Layout....25
10.1 Layout Guidelines....25
10.2 Layout Example....25
11 Device and Documentation Support....26
11.1 Documentation Support....26
11.2 Receiving Notification of Documentation Updates....26
11.3 Trademarks....26
12 Revision History....26
13 Mechanical, Packaging, and Orderable Information....26

Copyright © 2025 Texas Instruments Incorporated

4 Pin Configuration and Functions

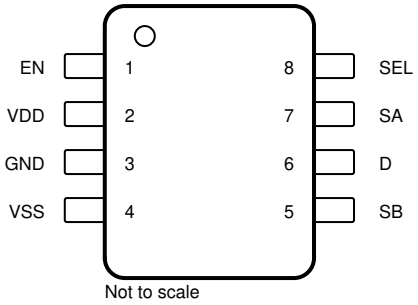


Figure 4-1. DCN Package 8-Pin SOT-23 Top View

Pin Functions

PIN		TYPE[1]	DESCRIPTION
NAME	NO.		
EN	1	I	Active high digital input. When this pin is low, both switches are turned off. When this pin is high, the SEL logic input determine which switch is turned on.
V_{DD}	2	P	Positive power supply. This pin is the most positive power-supply potential. For reliable operation, connect a decoupling capacitor ranging from 0.1µF to 10µF between V_{DD} and GND.
GND	3	P	Ground (0V) reference
V_{SS}	4	P	Negative power supply. This pin is the most negative power-supply potential. In single-supply applications, this pin can be connected to ground. For reliable operation, connect a decoupling capacitor ranging from 0.1µF to 10µF between V_{SS} and GND.
SB	5	I/O	Source pin B. Can be an input or output.
D	6	I/O	Drain pin. Can be an input or output.
SA	7	I/O	Source pin A. Can be an input or output.
SEL	8	I	Logic control input.

(1) I = input, O = output, I/O = input and output, P = power

Copyright © 2025 Texas Instruments Incorporated

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_{DD} to V_{SS}	Supply voltage		36	V
V_{DD} to GND		–0.3	18	V
V_{SS} to GND		–18	0.3	V
V_{DIG}	Digital input pin (SEL, EN) voltage	GND –0.3	V_{DD}+0.3	V
I_{DIG}	Digital input pin (SEL, EN) current	–30	30	mA
V_{ANA_IN}	Analog input pin (Sx) voltage	V_{SS}–0.3	V_{DD}+0.3	V
I_{ANA_IN}	Analog input pin (Sx) current	–30	30	mA
V_{ANA_OUT}	Analog output pin (D) voltage	V_{SS}–0.3	V_{DD}+0.3	V
I_{ANA_OUT}	Analog output pin (D) current	–30	30	mA
T_A	Ambient temperature	–55	140	°C
T_J	Junction temperature		150	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±500	

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Thermal Information

THERMAL METRIC(1)		TMUX6119 DCN (SOT-23) 8 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	180.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	138.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	90.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	73.7	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	90.5	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application note.

Copyright © 2025 Texas Instruments Incorporated

5.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{DD} to V_{SS} (1)	Power supply voltage differential	10		33	V
V_{DD} to GND	Positive power supply voltage (singlle supply, V_{SS} = 0V)	10		16.5	V
V_{DD} to GND	Positive power supply voltage (dual supply)	5		16.5	V
V_{SS} to GND	Negative power supply voltage (dual supply)	–16.5		–5	V
V_S (2)	Source pins voltage	V_{SS}		V_{DD}	V
V_D	Drain pin voltage	V_{SS}		V_{DD}	V
V_{DIG}	Digital input pin (SEL, EN) voltage	0		V_{DD}	V
I_{CH}	Channel current (T_A = 25°C)	–25		25	mA
T_A	Ambient temperature	–40		125	℃

(1) When V_{SS} = 0V, V_{DD} can range from 10V to 36V.
(2) V_{DD} and V_{SS} can be any value as long as 10V ≤ (V_{DD} – V_{SS}) ≤ 36V.

5.5 Electrical Characteristics (Dual Supplies: ±15V)

at T_A = 25°C, V_{DD} = 15V, and V_{SS} = -15V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
ANALOG SWITCH							
V_A	Analog signal range		T_A = –40°C to +125°C	V_{SS}		V_{DD}	V
R_{ON}	On-resistance	V_S = 0V, I_S = 1mA			120	135	Ω
		V_S = ±10V, I_S = 1mA			140	165	Ω
			T_A = –40°C to +85°C			210	Ω
			T_A = –40°C to +125°C			245	Ω
ΔR_{ON}	On-resistance mismatch between channels	V_S = ±10V, I_S = 1mA			2.4	6	Ω
			T_A = –40°C to +85°C			9	Ω
			T_A = –40°C to +125°C			11	Ω
R_{ON_FLAT}	On-resistance flatness	V_S = –10V, 0V, +10V, I_S = 1mA			22	45	Ω
			T_A = –40°C to +85°C			47	Ω
			T_A = –40°C to +125°C			49	Ω
R_{ON_DRIFT}	On-resistance drift	V_S = 0V			0.5		%/°C
$I_{S(OFF)}$	Source off leakage current(1)	Switch state is off, V_S = +10V/ –10V, V_D = –10V/ + 10V		–0.02	0.005	0.02	nA
			T_A = –40°C to +85°C	–0.12		0.05	nA
			T_A = –40°C to +125°C	–1		0.2	nA
$I_{D(OFF)}$	Drain off leakage current(1)	Switch state is off, V_S = +10V/ –10V, V_D = –10V/ +10V		–0.02	0.005	0.02	nA
			T_A = –40°C to +85°C	–0.12		0.05	nA
			T_A = –40°C to +125°C	–1		0.2	nA
$I_{D(ON)}$	Drain on leakage current	Switch state is on, V_S = +10V/ –10V, V_D = –10V/ +10V		–0.04	0.01	0.04	nA
			T_A = –40°C to +85°C	–0.25		0.1	nA
			T_A = –40°C to +125°C	–1.8		0.4	nA
DIGITAL INPUT (EN, Ax pins)							
V_{IH}	Logic voltage high			2			V
V_{IL}	Logic voltage low					0.8	V
$R_{PD(EN)}$	Pull-down resistance on EN pin				6		MΩ
POWER SUPPLY							

Copyright © 2025 Texas Instruments Incorporated

at T_A = 25°C, V_{DD} = 15V, and V_{SS} = -15V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{DD}	V_{DD} supply current	V_A = 0V or 3.3V, V_S = 0V			16	21	µA
			T_A = –40°C to +85°C			22	µA
			T_A = –40°C to +125°C			23	µA
I_{SS}	V_{SS} supply current	V_A = 0V or 3.3V, V_S = 0V			7	10	µA
			T_A = –40°C to +85°C			11	µA
			T_A = –40°C to +125°C			12	µA

(1) When V_S is positive, V_D is negative, and vice versa.

5.6 Switching Characteristics (Dual Supplies: ±15V)

at T_A = 25°C, V_{DD} = 15V, and V_{SS} = -15V (unless otherwise noted)[(1)]

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{ON}	Enable turn-on time	V_S = ±10V, R_L = 300Ω , C_L = 35pF		68	86	ns
		V_S = ±10V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +85°C			110	ns
		V_S = ±10V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C			121	ns
t_{OFF}	Enable turn-off time	V_S = ±10V, R_L = 300Ω , C_L = 35pF		57	64	ns
		V_S = ±10V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +85°C			78	ns
		V_S = ±10V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C			82	ns
t_{TRAN}	Transition time	V_S = 10V, R_L = 300Ω , C_L = 35pF		68	88	ns
		V_S = 10V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +85°C			99	ns
		V_S = 10V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C			106	ns
tBBM	Break-before-make time delay	V_S = 10V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C	8	37		ns
Q_J	Charge injection	V_S = 0V, R_S = 0Ω , C_L = 1nF		–0.19		pC
O_{ISO}	Off-isolation	R_L = 50Ω , C_L = 5pF, f = 1MHz		–85		dB
X_{TALK}	Channel-to-channel crosstalk	R_L = 50Ω , C_L = 5pF, f = 1MHz		–93		dB
I_L	Insertion loss	R_L = 50Ω , C_L = 5pF, f = 1MHz		-7.7		dB
ACPSRR	AC Power Supply Rejection Ratio	R_L = 10kΩ , C_L = 5pF, V_{PP}= 0.62V on V_{DD}, f= 1MHz		–55		dB
		R_L = 10kΩ , C_L = 5pF, V_{PP}= 0.62V on V_{SS}, f= 1MHz		–55		dB
BW	-3dB Bandwidth	R_L = 50Ω , C_L = 5pF		700		MHz
THD	Total harmonic distortion + noise	R_L = 10k Ω , C_L = 5pF, f= 20Hz to 20kHz		0.08		%
C_{IN}	Digital input capacitance	V_{IN} = 0V or V_{DD}		0.8		pF
$C_{S(OFF)}$	Source off-capacitance	V_S = 0V, f = 1MHz		1.9	2.8	pF
$C_{D(OFF)}$	Drain off-capacitance	V_S = 0V, f = 1MHz		4.3	4.7	pF
$C_{S(ON)}$, $C_{D(ON)}$	Source and drain on-capacitance	V_S = 0V, f = 1MHz		6.4	8.1	pF

(1) Specified by design; not subject to production testing.

Copyright © 2025 Texas Instruments Incorporated

5.7 Electrical Characteristics (Single Supply: 12V)

at T_A = 25°C, V_{DD} = 12V, and V_{SS} = 0V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
ANALOG SWITCH							
V_A	Analog signal range	T_A = –40°C to +125°C	T_A = –40°C to +125°C	V_{SS}		V_{DD}	V
R_{ON}	On-resistance	V_S = 10V, I_S = 1mA			230	265	Ω
			T_A = –40°C to +85°C			355	Ω
			T_A = –40°C to +125°C			405	Ω
ΔR_{ON}	On-resistance mismatch between channels	V_S = 10V, I_S = 1mA			1	9	Ω
			T_A = –40°C to +85°C			12	Ω
			T_A = –40°C to +125°C			14	Ω
R_{ON_DRIFT}	On-resistance drift	V_S = 0V			0.48		%/°C
$I_{S(OFF)}$	Source off leakage current(1)	Switch state is off, V_S = 10V/ 1V, V_D = 1V/ 10V		–0.02	0.005	0.02	nA
			T_A = –40°C to +85°C	–0.08		0.04	nA
			T_A = –40°C to +125°C	–0.75		0.13	nA
$I_{D(OFF)}$	Drain off leakage current(1)	Switch state is off, V_S = 10V/ 1V, V_D = 1V/ 10V		–0.02	0.005	0.02	nA
			T_A = –40°C to +85°C	–0.08		0.04	nA
			T_A = –40°C to +125°C	–0.75		0.13	nA
$I_{D(ON)}$	Drain on leakage current	Switch state is on, V_S = floating, V_D = 1V/ 10V		–0.04	0.01	0.04	nA
			T_A = –40°C to +85°C	–0.16		0.08	nA
			T_A = –40°C to +125°C	–1.5		0.25	nA
DIGITAL INPUT (EN, Ax pins)							
V_{IH}	Logic voltage high			2			V
V_{IL}	Logic voltage low					0.8	V
$R_{PD(EN)}$	Pull-down resistance on EN pin				6		MΩ
POWER SUPPLY							
I_{DD}	V_{DD} supply current	V_A = 0V or 3.3V, V_S = 0V			11	14	µA
			T_A = –40°C to +85°C			16	µA
			T_A = –40°C to +125°C			17	µA

(1) When V_S is positive, V_D is negative, and vice versa.

Copyright © 2025 Texas Instruments Incorporated

5.8 Switching Characteristics (Single Supply: 12V)

at T_A = 25°C, V_{DD} = 12V, and V_{SS} = 0V (unless otherwise noted)(1)

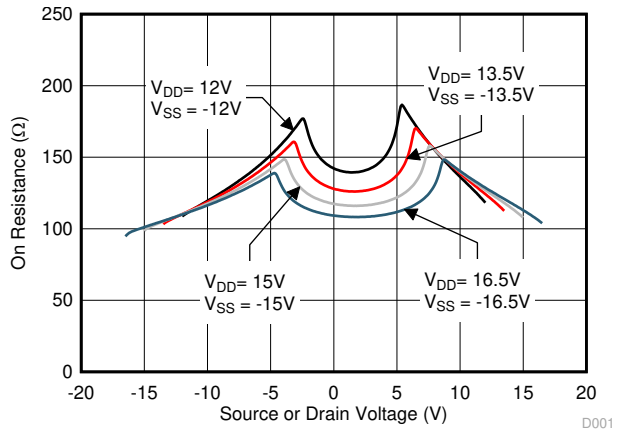
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{ON}	Enable turn-on time	V_S = 8V, R_L = 300Ω , C_L = 35pF		73	91	ns
		V_S = 8V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +85°C			119	ns
		V_S = 8V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C			130	ns
t_{OFF}	Enable turn-off time	V_S = 8V, R_L = 300Ω , C_L = 35pF		60	69	ns
		V_S = 8V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +85°C			82	ns
		V_S = 8V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C			88	ns
t_{TRAN}	Transition time	V_S = 8V, R_L = 300Ω , C_L = 35pF		73	93	ns
		V_S = 8V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +85°C			104	ns
		V_S = 8V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C			112	ns
t_{BBM}	Break-before-make time delay	V_S = 8V, R_L = 300Ω , C_L = 35pF, T_A = –40°C to +125°C	10	45		ns
Q_J	Charge injection	V_S = 6V, R_S = 0Ω , C_L = 1nF		0.1		pC
O_{ISO}	Off-isolation	R_L = 50Ω , C_L = 5pF, f = 1MHz		-85		dB
X_{TALK}	Channel-to-channel crosstalk	R_L = 50Ω , C_L = 5pF, f = 1MHz		–100		dB
I_L	Insertion loss	R_L = 50Ω , C_L = 5pF, f = 1MHz		-15		dB
ACPSRR	AC Power Supply Rejection Ratio	R_L = 10kΩ , C_L = 5pF, V_{PP}= 0.62V, f= 1MHz		–55		dB
BW	-3dB Bandwidth	R_L = 50Ω , C_L = 5pF		440		MHz
C_{IN}	Digital input capacitance	V_{IN} = 0V or V_{DD}		1		pF
$C_{S(OFF)}$	Source off-capacitance	V_S = 6V, f = 1MHz		2	2.9	pF
$C_{D(OFF)}$	Drain off-capacitance	V_S = 6V, f = 1MHz		4.9	5.3	pF
$C_{S(ON)}$, $C_{D(ON)}$	Source and drain on-capacitance	V_S = 6V, f = 1MHz		7.4	8.9	pF

(1) Specified by design; not subject to production testing.

Copyright © 2025 Texas Instruments Incorporated

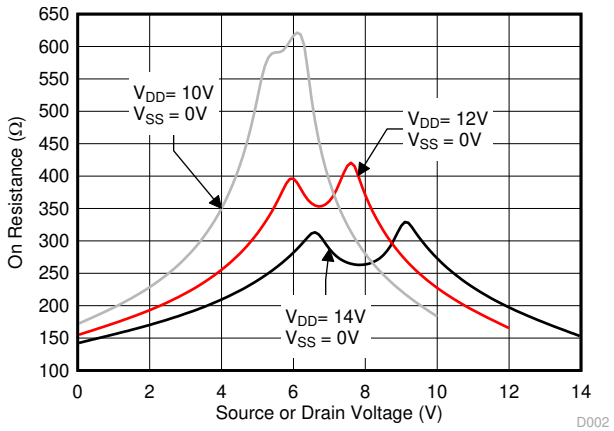
5.9 Typical Characteristics

at T_A = 25°C, V_{DD} = 15V, and V_{SS} = –15V (unless otherwise noted)



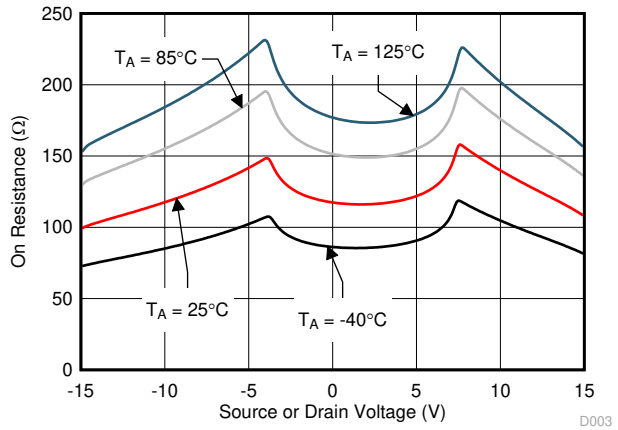
Dual Supply Operation (T_A = 25°C)

Figure 5-1. On-Resistance vs Source or Drain Voltage



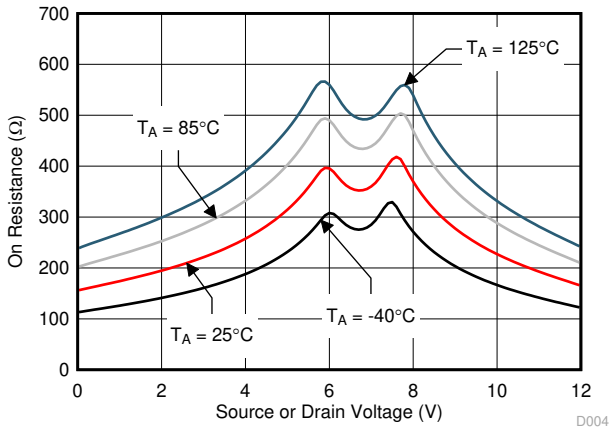
Single Supply Operation (T_A = 25°C)

Figure 5-2. On-Resistance vs Source or Drain Voltage



V_{DD} = 15V, V_{SS} = –15V

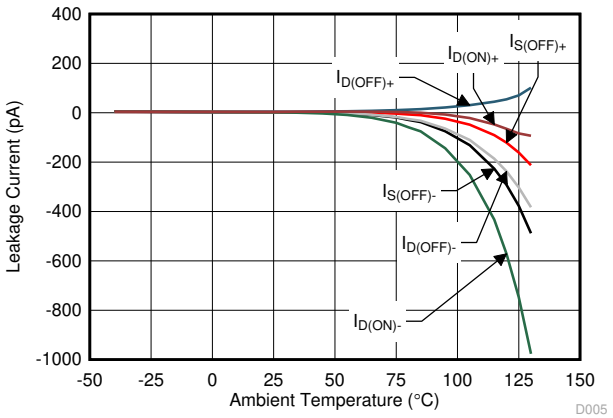
Figure 5-3. On-Resistance vs Source or Drain Voltage



V_{DD} = 12V, V_{SS} = 0V

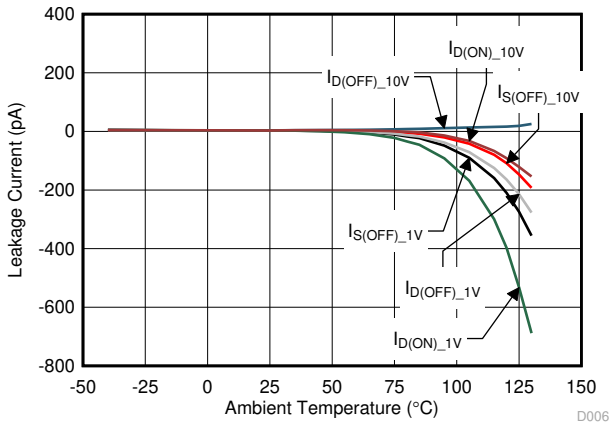
Figure 5-4. On-Resistance vs Source or Drain Voltage

Copyright © 2025 Texas Instruments Incorporated



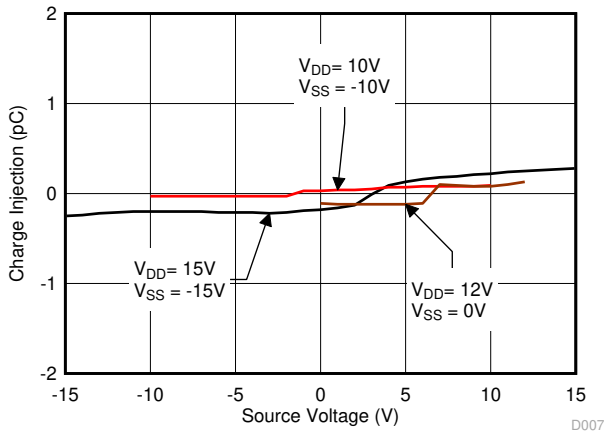
V_{DD} = 15V, V_{SS} = –15V

Figure 5-5. . Leakage Current vs Temperature



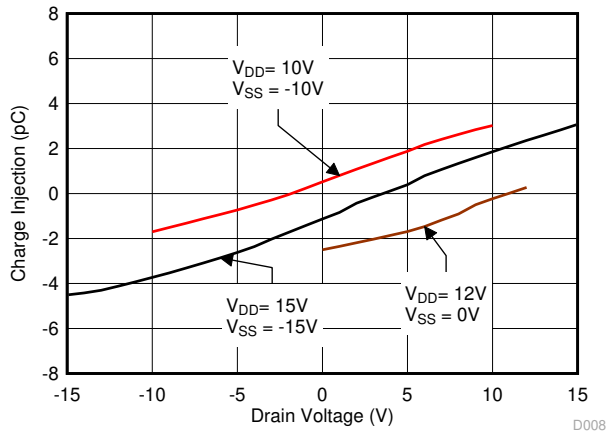
V_{DD} = 12V, V_{SS} = 0V

Figure 5-6. Leakage Current vs Temperature



T_A = 25°C

Figure 5-7. Charge Injection vs Source Voltage



T_A = 25°C

Figure 5-8. Charge Injection vs Drain Voltage

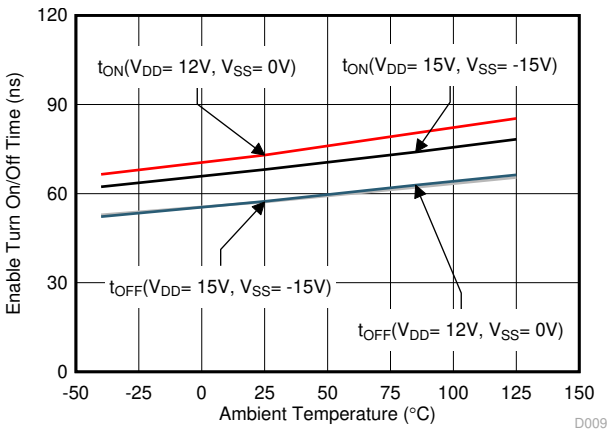
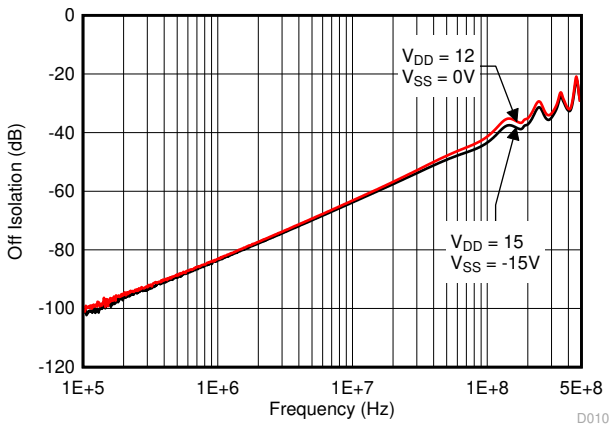


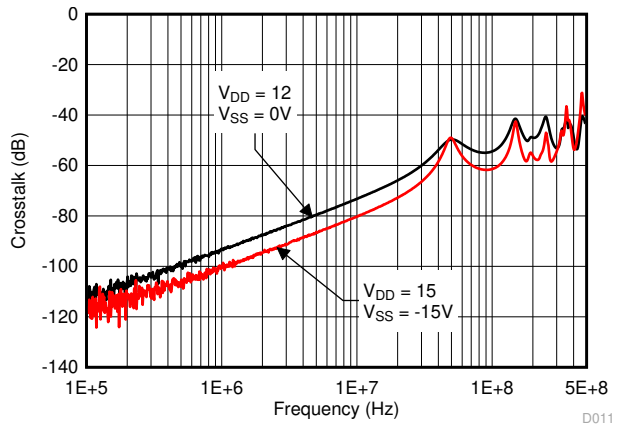
Figure 5-9. Enable turn-on and turn-off time



T_A = 25°C

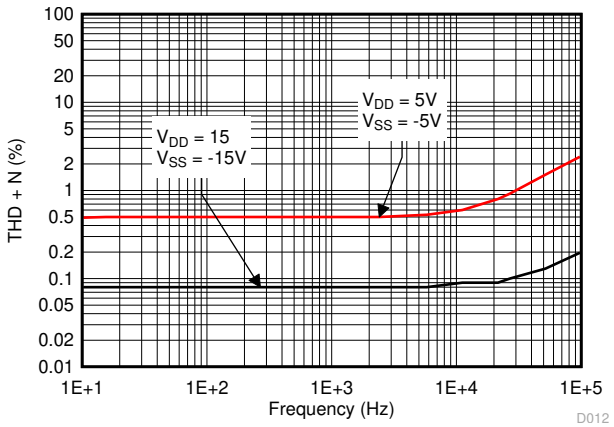
Figure 5-10. Off Isolation vs Frequency

Copyright © 2025 Texas Instruments Incorporated



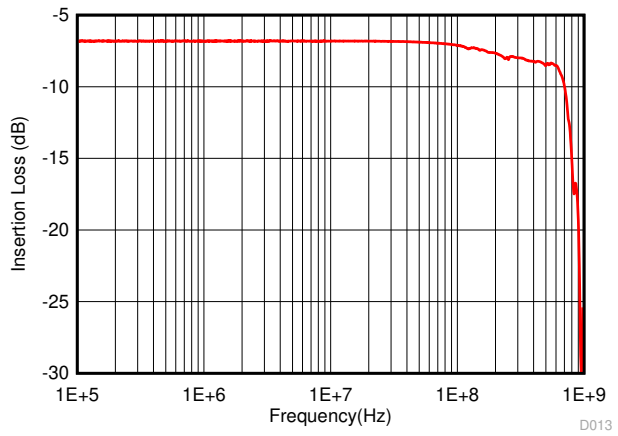
T_A = 25°C

Figure 5-11. Crosstalk vs Frequency



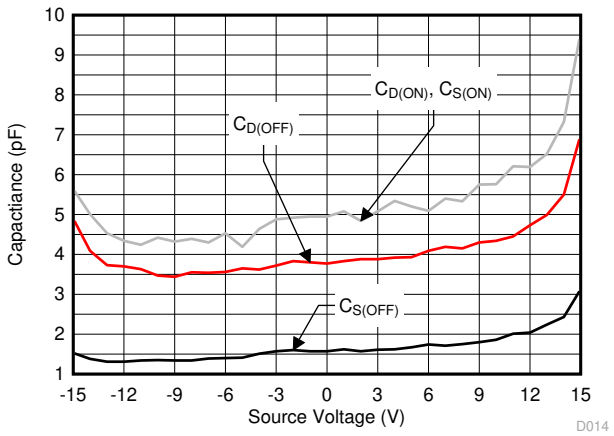
T_A = 25°C

Figure 5-12. THD+N vs Frequency



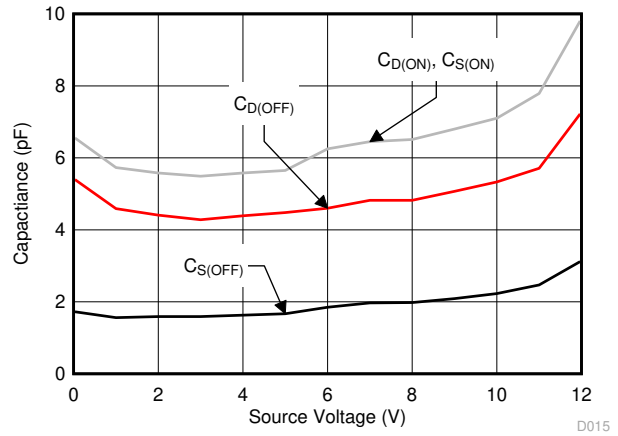
V_{DD} = 15V, V_{SS} = –15V, T_A = 25°C

Figure 5-13. On Response vs Frequency



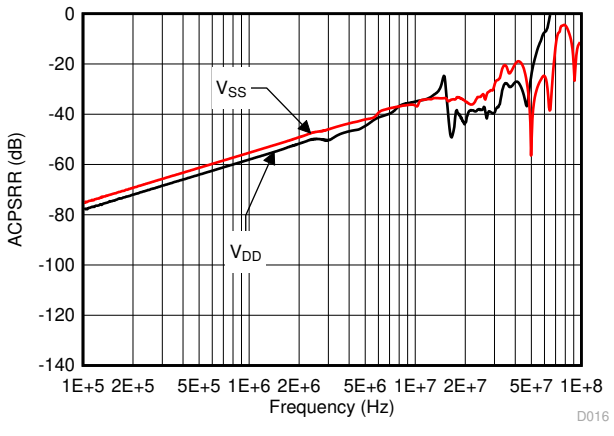
V_{DD} = 15V, V_{SS} = –15V, T_A = 25°C

Figure 5-14. Capacitance vs Source Voltage



V_{DD} = 12V, V_{SS} = 0V, T_A = 25°C

Figure 5-15. Capacitance vs Source Voltage



V_{DD} = 15V, V_{SS} = –15V, T_A = 25°C

Figure 5-16. ACPSRR vs Frequency

6 Parameter Measurement Information

6.1 Truth Tables

Table 6-1 shows the truth tables for theTMUX6119.

Table 6-1. TMUX6119 Truth Table

EN	SEL	STATE	
		Switch A (SA to D)	Switch B (SB to D)
0	X(1)	OFF	OFF
1	0	ON	OFF
1	1	OFF	ON

(1) X denotes *do not care*.

Copyright © 2025 Texas Instruments Incorporated

7 Detailed Description

7.1 Overview

The TMUX6119 has a low on and off leakage currents and ultra-low charge injection, allowing the device to be used in high precision measurement applications. The device also provides excellent isolation capability by blocking signal levels up to the supplies when the switches are in the OFF position. A low supply current of 17µA enables usage in portable applications.

7.1.1 On-Resistance

The on-resistance of the TMUX6119 is the ohmic resistance across the source (SA or SB) and drain (D) pins of the device. The on-resistance varies with input voltage and supply voltage. The symbol R_{ON} is used to denote on-resistance. The measurement setup used to measure R_{ON} is shown in Figure 7-1. Voltage (V) and current (I_{CH}) are measured using this setup, and R_{ON} is computed as shown in Equation 1:

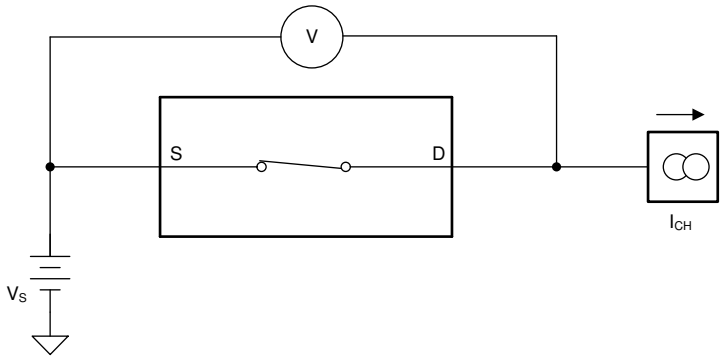


Figure 7-1. On-Resistance Measurement Setup

$$R_{ON} = V / I_{CH} \quad (1)$$

7.1.2 Off-Leakage Current

There are two types of leakage currents associated with a switch during the off state:

1. Source off-leakage current
2. Drain off-leakage current

Source leakage current is defined as the leakage current flowing into or out of the source pin when the switch is off. This current is denoted by the symbol $I_{S(OFF)}$.

Drain leakage current is defined as the leakage current flowing into or out of the drain pin when the switch is off. This current is denoted by the symbol $I_{D(OFF)}$.

The setup used to measure both off-leakage currents is shown in Figure 7-2.

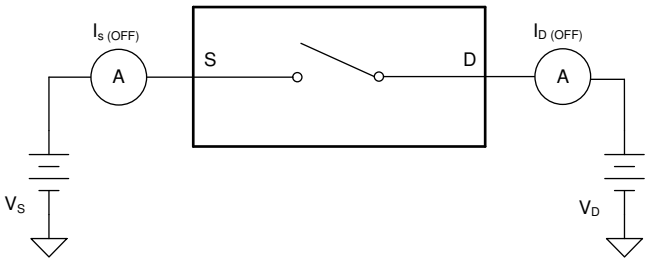


Figure 7-2. Off-Leakage Measurement Setup

7.1.3 On-Leakage Current

On-leakage current is defined as the leakage current that flows into or out of the drain pin when the switch is in the on state. The source pin is left floating during the measurement. Figure 7-3 shows the circuit used for measuring the on-leakage current, denoted by $I_{D(ON)}$.

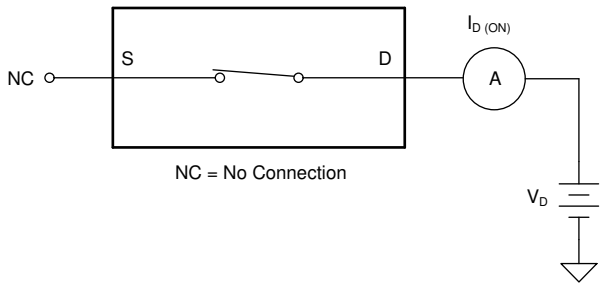


Figure 7-3. On-Leakage Measurement Setup

7.1.4 Transition Time

Transition time is defined as the time taken by the output of the TMUX6119 to rise or fall to 90% of the transition after the digital address signal has fallen or risen to 50% of the transition. Figure 7-4 shows the setup used to measure transition time, denoted by the symbol t_t.

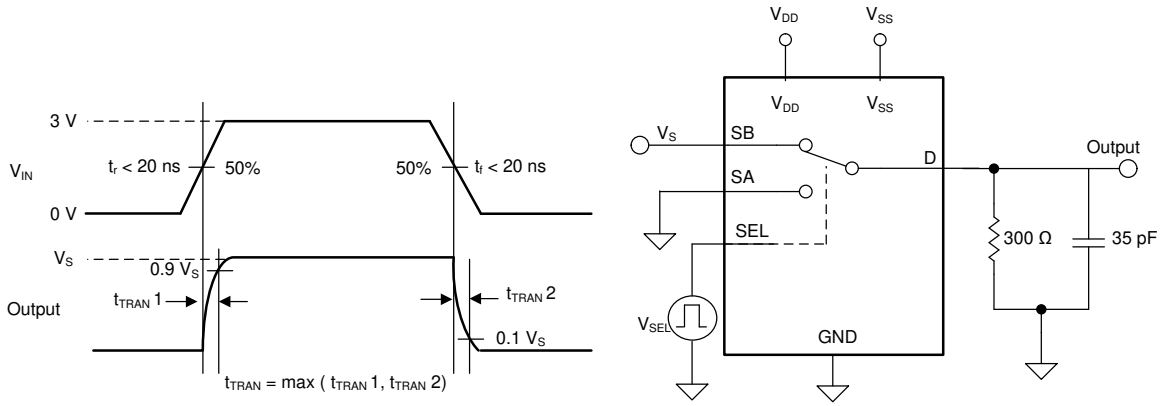


Figure 7-4. Transition-Time Measurement Setup

Copyright © 2025 Texas Instruments Incorporated

7.1.5 Break-Before-Make Delay

Break-before-make delay is a safety feature that prevents two inputs from connecting when the TMUX6119 is switching. The TMUX6119 output first breaks from the on-state switch before making the connection with the next on-state switch. The time delay between the *break* and the *make* is known as break-before-make delay. Figure 7-5 shows the setup used to measure break-before-make delay, denoted by the symbol t_{BBM}.

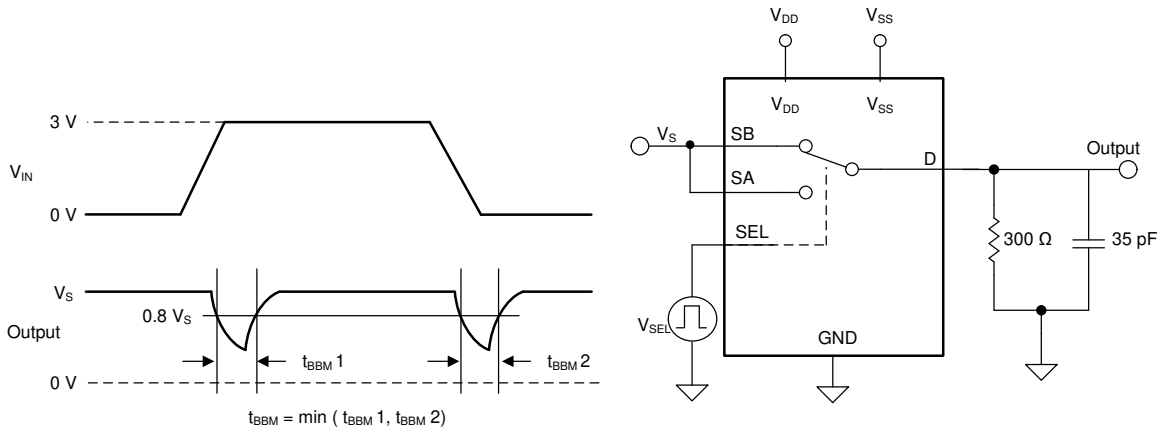


Figure 7-5. Break-Before-Make Delay Measurement Setup

7.1.6 Enable Turn-On and Enable Turn-Off Time

Enable turn-on time is defined as the time taken by the output of the TMUX6119 to rise to a 90% final value after the EN signal has risen to a 50% final value. Figure 7-6 shows the setup used to measure turn-on time. Enable turn-on time is denoted by the symbol t_{ON}.

Enable turn off time is defined as the time taken by the output of the TMUX6119 to fall to a 10% initial value after the EN signal has fallen to a 50% initial value. Figure 7-6 shows the setup used to measure turn-off time. Enable Turn-off time is denoted by the symbol t_{OFF}.

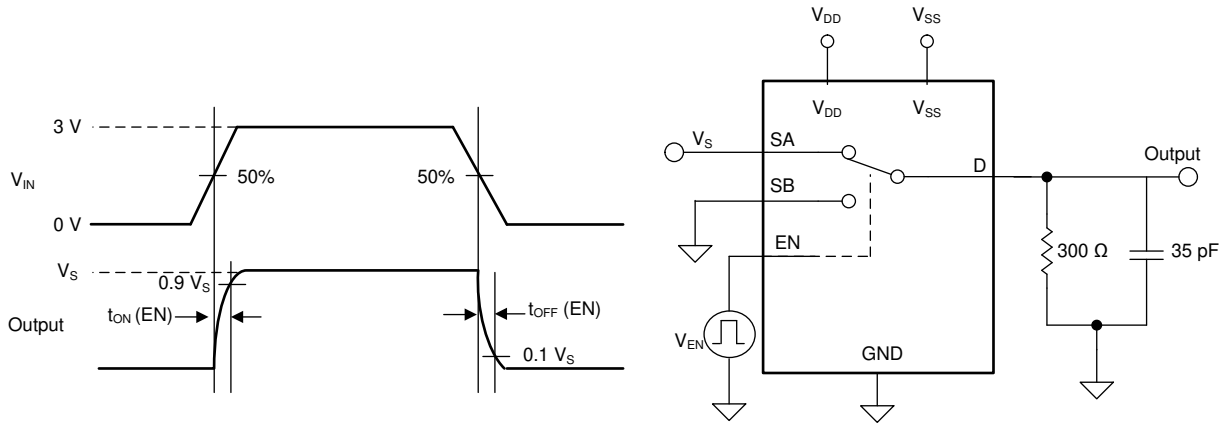


Figure 7-6. Turn-On and Turn-Off Time Measurement Setup

7.1.7 Charge Injection

The TMUX6119 have a simple transmission-gate topology. Any mismatch in capacitance between the NMOS and PMOS transistors results in a charge injected into the drain or source during the falling or rising edge of the gate signal. The amount of charge injected into the source or drain of the device is known as charge injection, and is denoted by the symbol Q_{INJ}. Figure 7-7 and Figure 7-8 shows the setup used to measure charge injection from source to drain and from drain to source. The charge injection is optimized for the TMUX6119 from the direction of source to drain.

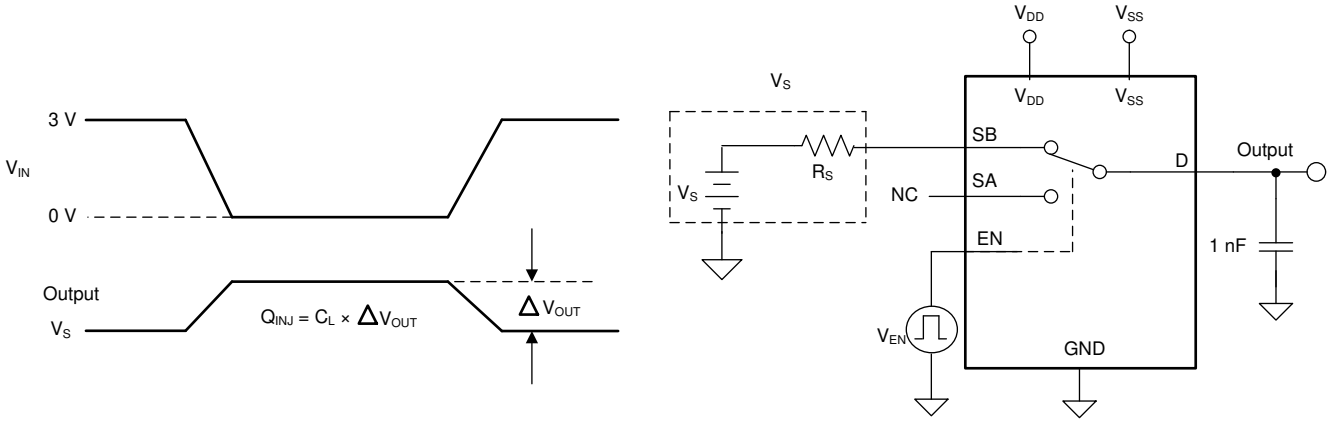


Figure 7-7. Source to Drain Charge-Injection Measurement Setup

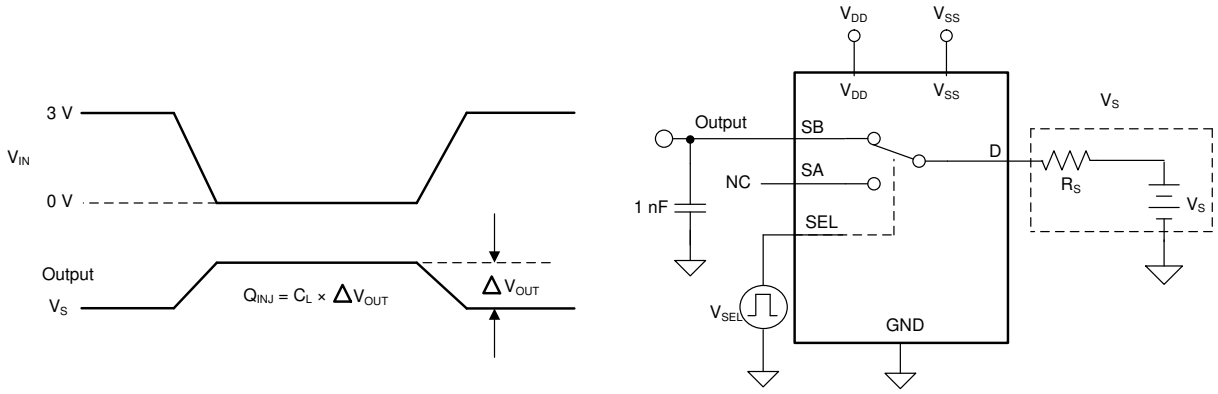


Figure 7-8. Drain to Source Charge-Injection Measurement Setup

7.1.8 Off Isolation

Off isolation is defined as the voltage at the drain pin (D) of the TMUX6119 when a 1-V_{RMS} signal is applied to the source pin (SA or SB) of an off-channel. Figure 7-9 shows the setup used to measure off isolation. Use to Equation 2 compute off isolation.

Copyright © 2025 Texas Instruments Incorporated

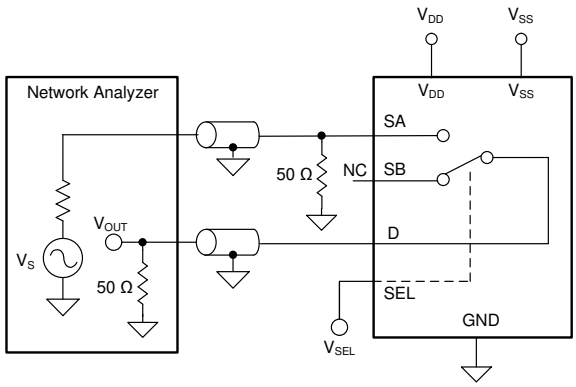


Figure 7-9. Off Isolation Measurement Setup

$$Off\ Isolation = 20\ \times\ Log\left(\frac{V_{OUT}}{V_S}\right) \quad (2)$$

7.1.9 Channel-to-Channel Crosstalk

Channel-to-channel crosstalk is defined as the voltage at the source pin (SA or SB) of an off-channel, when a 1-V_{RMS} signal is applied at the source pin of an on-channel. Figure 7-10 shows the setup used to measure, and Equation 3 is the equation used to compute channel-to-channel crosstalk.

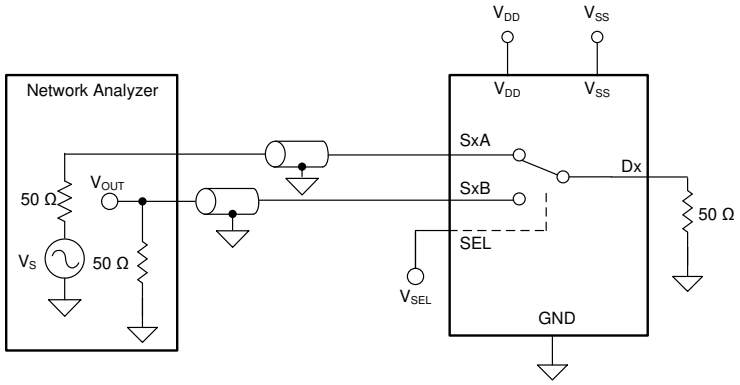


Figure 7-10. Channel-to-Channel Crosstalk Measurement Setup

$$Channel - to - Channel\ Crosstalk = 20\ \times\ Log\left(\frac{V_{OUT}}{V_S}\right) \quad (3)$$

7.1.10 Bandwidth

Bandwidth is defined as the range of frequencies that are attenuated by < 3dB when the input is applied to the source pin of an on-channel, and the output is measured at the drain pin of the TMUX6119. Figure 7-11 shows the setup used to measure bandwidth of the mux. Use Equation 4 to compute the attenuation.

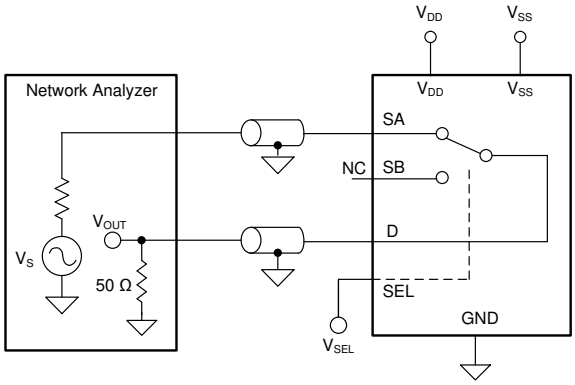


Figure 7-11. Bandwidth Measurement Setup

$$Attenuation = 20 \times Log\left(\frac{V_2}{V_1}\right) \quad (4)$$

7.1.11 THD + Noise

The total harmonic distortion (THD) of a signal is a measurement of the harmonic distortion, and is defined as the ratio of the sum of the powers of all harmonic components to the power of the fundamental frequency at the mux output. The on-resistance of the TMUX6119 varies with the amplitude of the input signal and results in distortion when the drain pin is connected to a low-impedance load. Total harmonic distortion plus noise is denoted as THD+N. Figure 7-12 shows the setup used to measure THD+N of the TMUX6119.

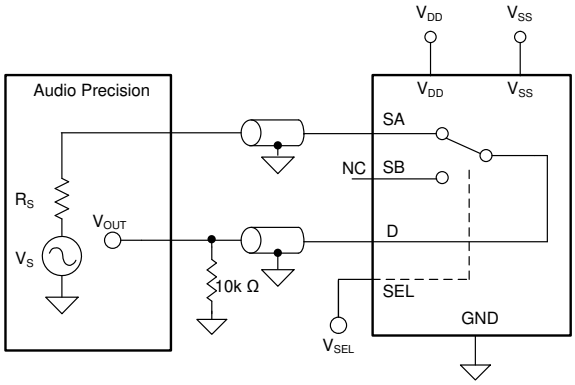


Figure 7-12. THD+N Measurement Setup

Copyright © 2025 Texas Instruments Incorporated

7.1.12 AC Power Supply Rejection Ratio (AC PSRR)

AC PSRR measures the ability of a device to prevent noise and spurious signals that appear on the supply voltage pin from coupling to the output of the switch. The DC voltage on the device supply is modulated by a sine wave of 620mVPP. The ratio of the amplitude of signal on the output to the amplitude of the modulated signal is the AC PSRR. Figure 7-13 shows the setup used to measure ACPSRR of the TMUX6119.

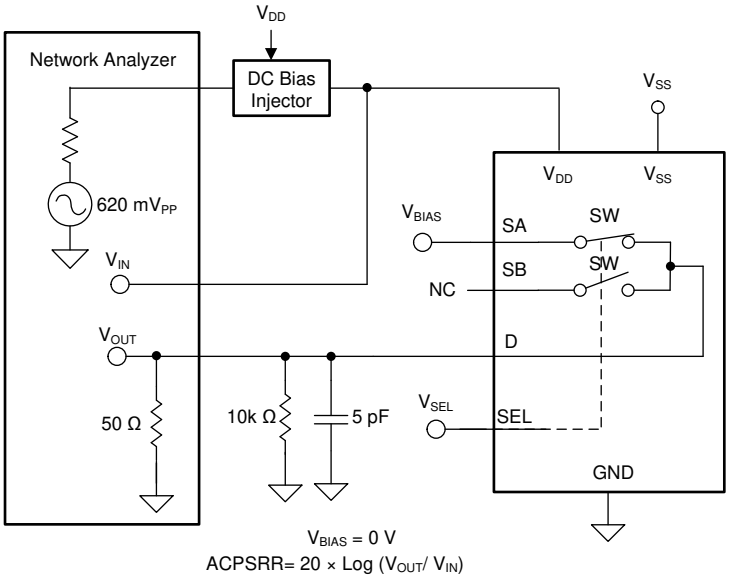
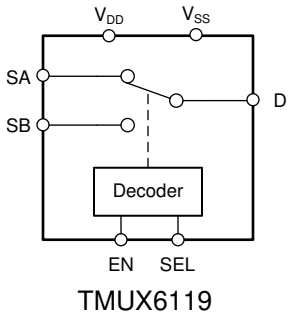


Figure 7-13. AC PSRR Measurement Setup

7.2 Functional Block Diagram



TMUX6119

7.3 Feature Description

7.3.1 Ultra-low Leakage Current

The TMUX6119 provide extremely low on- and off-leakage currents. The TMUX6119 is capable of switching signals from high source-impedance inputs into a high input-impedance op amp with minimal offset error because of the ultralow leakage currents. Figure 7-14 shows typical leakage currents of the TMUX6119 versus temperature.

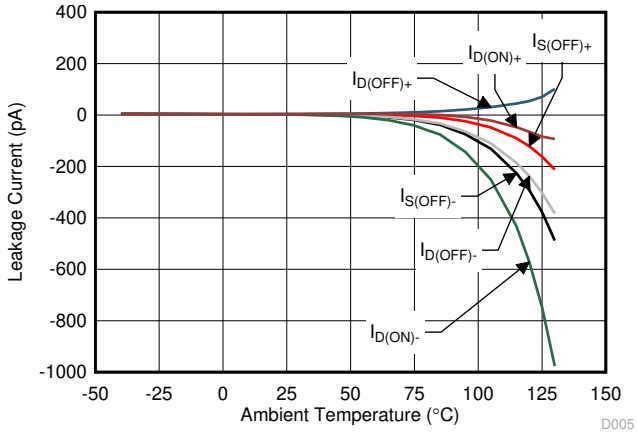


Figure 7-14. Leakage Current vs Temperature

7.3.2 Ultra-low Charge Injection

The TMUX6119 is implemented with simple transmission gate topology, as shown in Figure 7-15. Any mismatch in the stray capacitance associated with the NMOS and PMOS causes an output level change whenever the switch is opened or closed.

Copyright © 2025 Texas Instruments Incorporated

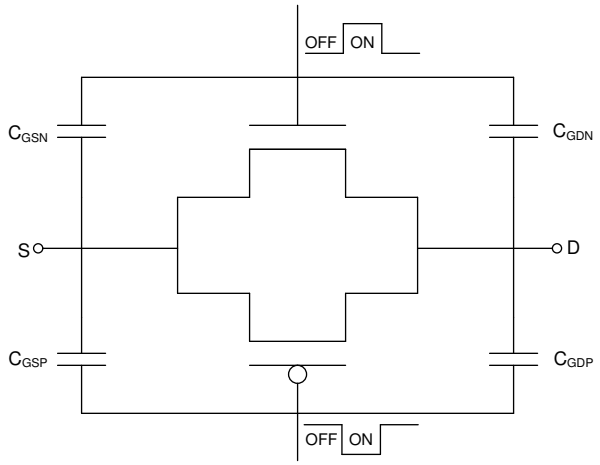


Figure 7-15. Transmission Gate Topology

The TMUX6119 utilizes special charge-injection cancellation circuitry that reduces the source (SA or SB)-to-drain (D) charge injection to as low as 0.19pC at V_S = 0V, as shown in Figure 7-16.

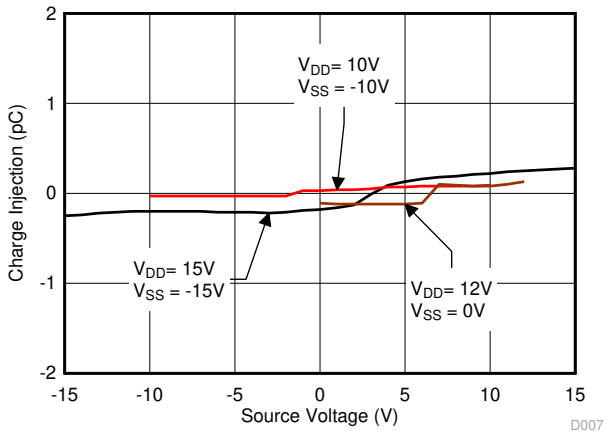


Figure 7-16. Charge Injection vs Source Voltage

The drain (D)-to-source (SA or SB) charge injection becomes important when the device is used as a demultiplexer (demux), where D becomes the input and Sx becomes the output. Figure 7-17 shows the drain-to-source charge injection across the full signal range.

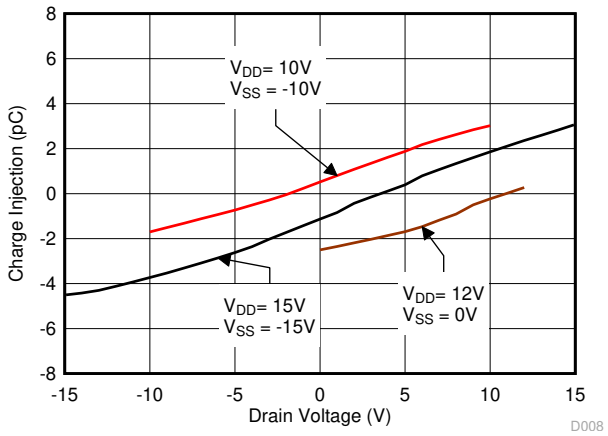


Figure 7-17. Charge Injection vs Drain Voltage

7.3.3 Bidirectional and Rail-to-Rail Operation

The TMUX6119 conducts equally well from source (SA or SB) to drain (D) or from drain (D) to source (SA or SB). Each TMUX6119 channel has very similar characteristics in both directions. The valid analog signal for TMUX6119 ranges from V_{SS} to V_{DD}. The input signal to the TMUX6119 swings from V_{SS} to V_{DD} without any significant degradation in performance.

7.4 Device Functional Modes

When the EN pin of the TMUX6119 is pulled high, one of the two switches is closed based on the state of the SEL pin. When the EN pin is pulled low, both switches remain open irrespective of the state of the SEL pin. The EN pin is weakly pull-down internally through a 6MΩ resistor, thereby setting each channel to the open state if the EN pin is not actively driven. The SEL pin is also weakly pulled-down through an internal 6Mohm resistor, allowing channel A (SA to D) to be selected by default when EN pin is driven high. Both the EN pin and the SEL pin can be connected to V_{DD} (as high as 16.5V).

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TMUX6119 offers outstanding input / output leakage current and ultra-low charge injection performance. The on-capacitance of the TMUX6119 is also very low. These properties make the TMUX6119 ideal for implementing high precision industrial systems requiring selection of one of two inputs or outputs.

8.2 Typical Application

One application to take advantage of TMUX6119's precision performance is the implementation of the chopper amplifier. The chopper amplifier was developed in the 1950s to achieve ultra-low offset voltage and low offset voltage drift over time and temperature. It also drastically reduces low frequency 1/f (flicker) noise. These attributes make the chopper amplifier ideal for small signal conditioning. Figure 8-1 illustrates a classic example of a simple chopper amplifier implemented with two TMUX6119 SPDT switches.

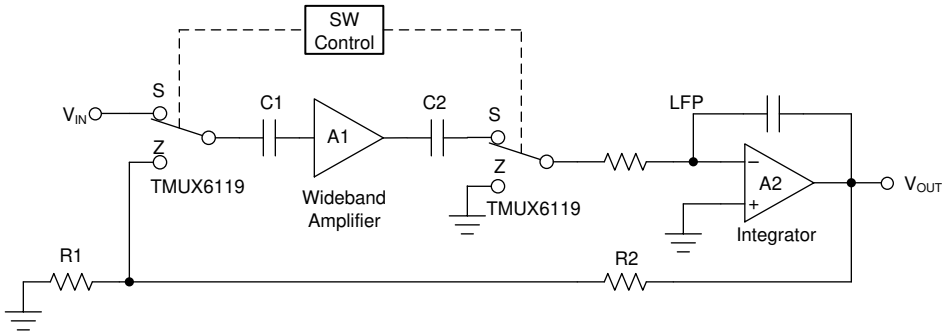


Figure 8-1. Example of classic chopper amplifier implemented with two TMUX6119

8.2.1 Design Requirements

The goal of a chopper-amplifier design is to produce extremely high DC precision by continuously self-cancelling input offset voltage even during variations in temperature, time, common-mode voltage, and power supply voltage, while reducing low-frequency 1/f (flicker) voltage.

Copyright © 2025 Texas Instruments Incorporated

8.2.2 Detailed Design Procedure

The theory of operation for the chopper amplifier relies on the concept of converting a DC input signal to AC before feeding it into an AC-coupled wideband amplifier. The conversion utilizes a SPDT switches to “chop” the input DC signal into an AC voltage. The output of the amplifier is then modulated by another SPDT switch to convert the signal back to DC. The output of the switch is then low-pass filtered (or integrated) to smooth and produce the final DC output.

The operation of the chopper amplifier consists of 2 phases, the sampling (S) phase and the auto-zero (Z) phase. During the auto-zero phase, the switches are toggled to the Z position, and capacitors C1 and C2 are charged to the amplifier input and output offset voltage, respectively. During the sampling phase, the switches are toggled to the S position, during which VIN is connected to VOUT through C1, the wideband amplifier, C2, and the integrator. Input DC voltage is AC-coupled by capacitor C1 and amplified by the wideband amplifier A1. C2 helps reduce any DC component caused by the amplifier’s input offset voltage, and the integrator helps smooth out the output signals to produce desired DC voltage output.

Several mechanisms helps reduce overall noise of the chopper-amplifier design. The DC gain, being the product of the AC stage and the DC gain of the integrator, can easily reach an open-loop gain of 160dB or higher and therefore reduce the gain error, V_{OUT}/ (A1×A2) to almost zero. The offset and drift in the output integrator stage are nulled by the DC gain of the preceding AC stage. DC drifts in the AC stage are also non-factors because the amplification stage is AC-coupled. The 1/f noise of the wideband amplifier is modulated to higher frequencies by the demodulator.

Note that the input signal frequency shall be much less than one-half of the chopping frequency to prevent aliasing errors in this chopper amplifier implementation. The chopper frequency, in turn, is restricted by the wideband amplifier’s gain-phase limitations as well as errors induced by switch transition time and charge injection. The TMUX6119 ‘s switch transition time is only 68ns (typ) and average charge injection is less than 0.19pC, making it ideal for the chopper amplifier implementation. However, the input signal frequency is still limited by the amplifier’s performance. If higher sampling frequency is required, a chopper-stabilized amplifier, or an integrated zero-drift amplifier (such as the OPA2188), can be used to satisfy the requirement.

8.2.3 Application Curve

Fast transition time and small charge injection are two critical parameters for the SPDT switches used in the chopper amplifier design. Figure 8-2 shows the plot for the charge injection vs. source voltage for the TMUX6119.

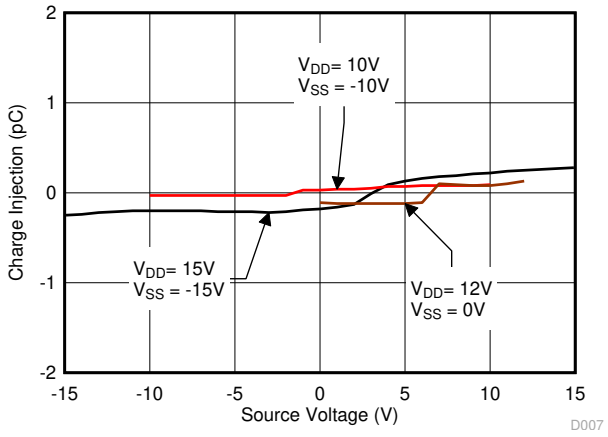


Figure 8-2. Charge Injection vs Source Voltage

9 Power Supply Recommendations

The TMUX6119 operates across a wide supply range of ±5V to ±16.5V (10V to 16.5V in single-supply mode). They also perform well with unsymmetric supplies such as V_{DD} = 12V and V_{SS}= –5V. For reliable operation, use a supply decoupling capacitor ranging between 0.1µF to 10µF at both the V_{DD} and V_{SS} pins to ground.

The on-resistance of the TMUX6119 varies with supply voltage, as illustrated in Figure 9-1.

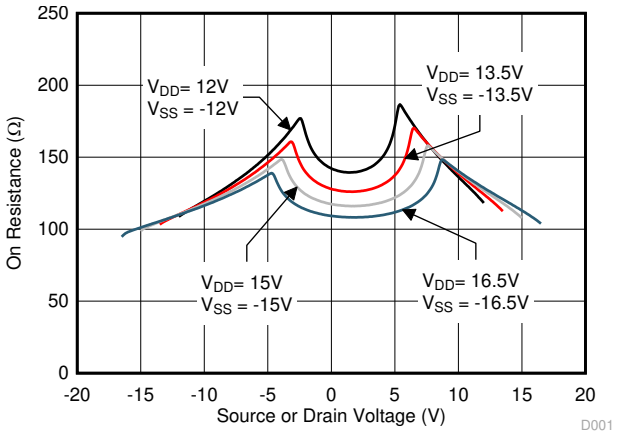


Figure 9-1. On-Resistance Variation With Supply and Input Voltage

Copyright © 2025 Texas Instruments Incorporated

10 Layout

10.1 Layout Guidelines

Figure 10-1 shows an example of a PCB layout with the TMUX6119.

Some key considerations are:

1. Decouple the V_{DD} and V_{SS} pins with a 0.1µF capacitor, placed as close to the pin as possible. Make sure that the capacitor voltage rating is sufficient for the V_{DD} and V_{SS} supplies.
2. Keep the input lines as short as possible. In case of the differential signal, make sure the A inputs and B inputs are as symmetric as possible.
3. Use a solid ground plane to help distribute heat and reduce electromagnetic interference (EMI) noise pickup.
4. Do not run sensitive analog traces in parallel with digital traces. Avoid crossing digital and analog traces if possible, and only make perpendicular crossings when necessary.

10.2 Layout Example

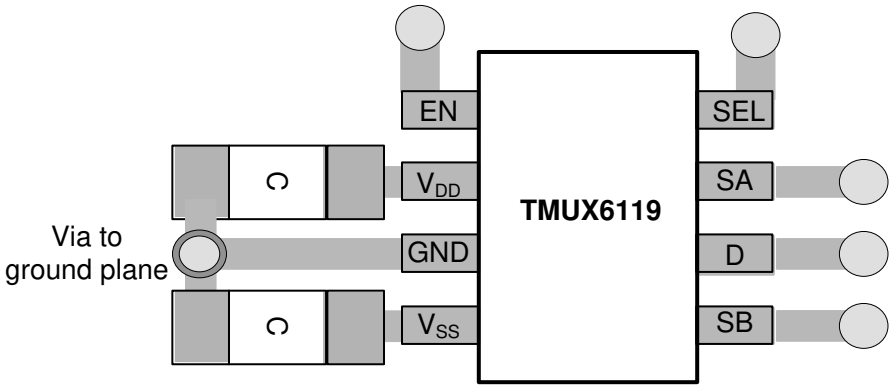


Figure 10-1. TMUX6119 Layout Example

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

- Texas Instruments, *OPA2188 0.03-µV/°C Drift, Low-Noise, Rail-to-Rail Output, 36-V, Zero-Drift Operational Amplifiers*

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 Trademarks

All trademarks are the property of their respective owners.

12 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (December 2018) to Revision B (August 2025)	Page
• Updated low input leakage from 0.5pA to 5pA	1

Changes from Revision * (September 2018) to Revision A (December 2018)	Page
• Changed the document status from *Advanced Information* to *Production Data*	1

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Copyright © 2025 Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMUX6119DCNR	Active	Production	SOT-23 (DCN) | 8	3000 | LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	1QAC
TMUX6119DCNR.B	Active	Production	SOT-23 (DCN) | 8	3000 | LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	1QAC

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

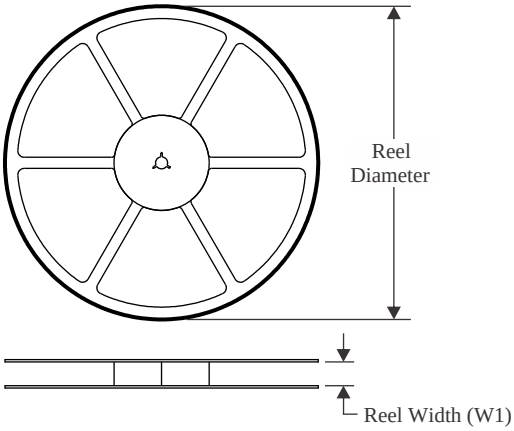
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

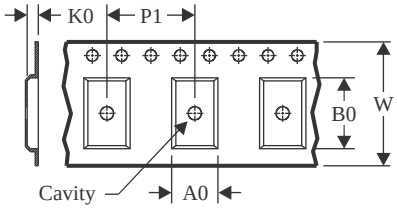
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

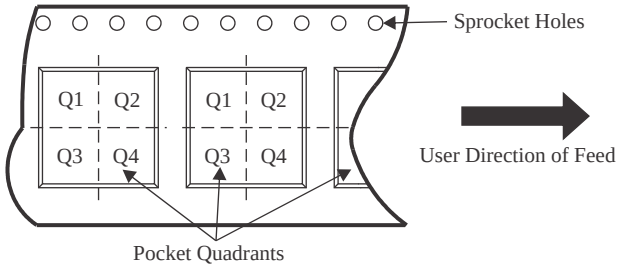


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

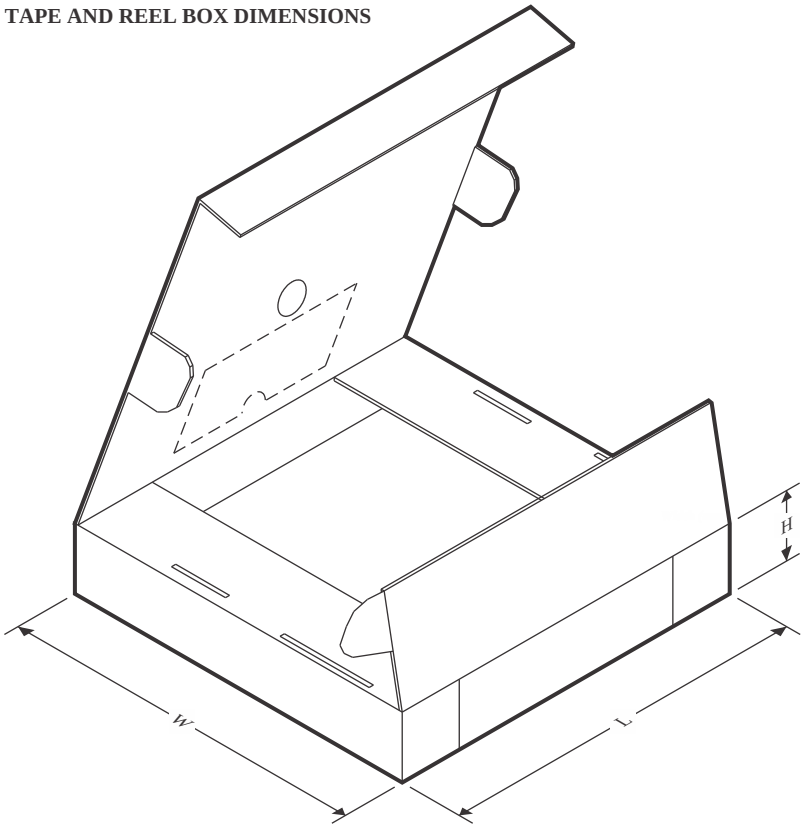
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMUX6119DCNR	SOT-23	DCN	8	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3

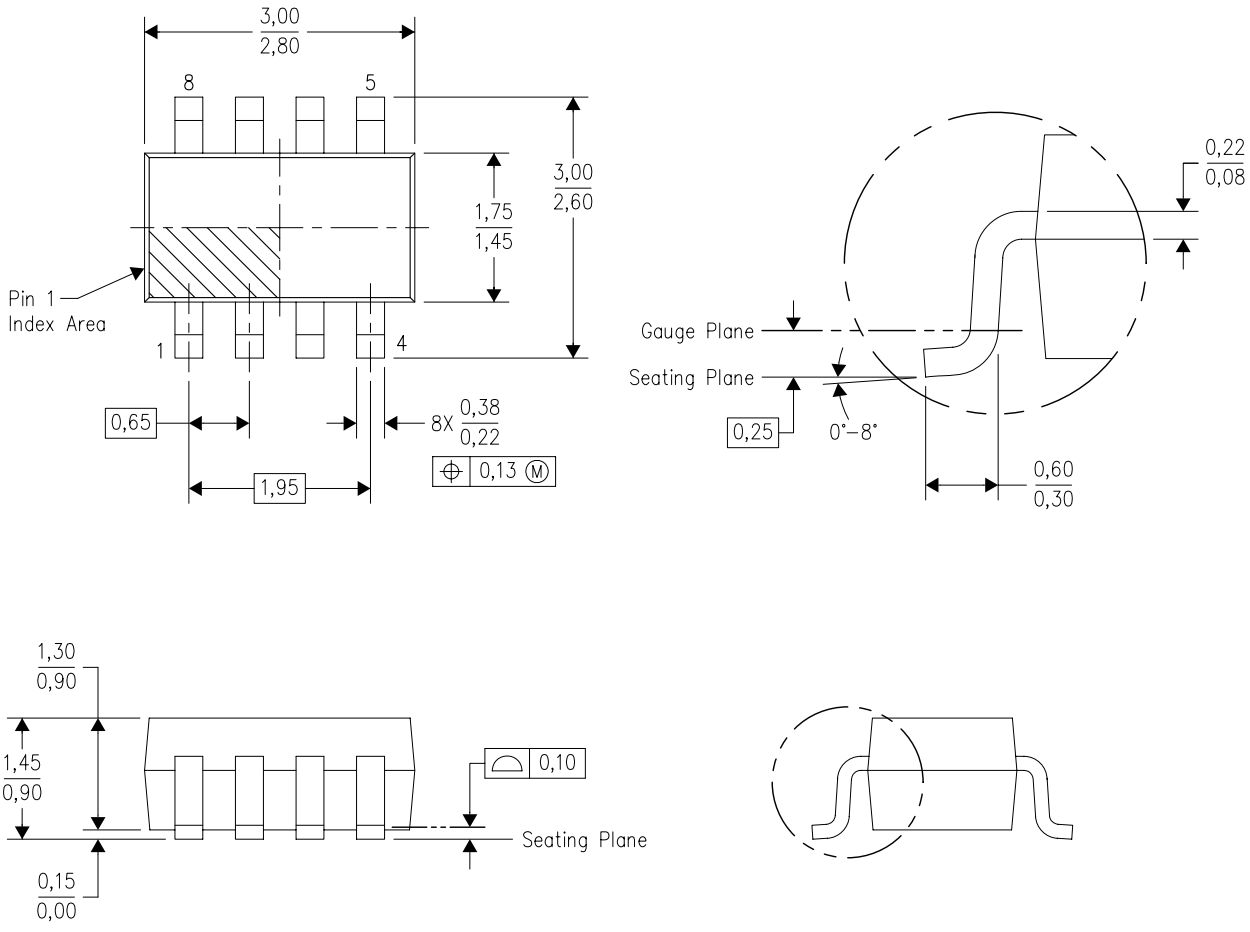
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMUX6119DCNR	SOT-23	DCN	8	3000	183.0	183.0	20.0

DCN (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE (DIE DOWN)



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Package outline exclusive of metal burr & dambar protrusion/intrusion.
D. Package outline inclusive of solder plating.
E. A visual index feature must be located within the Pin 1 index area.
F. Falls within JEDEC MO–178 Variation BA.
G. Body dimensions do not include flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025